

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BFS	L1	116	wafer and interposer and glass	USEPAT; EPC; JPC; DEFWEN T; IBM_TD B	2002/07/15 11:00
2	BFS	L2	74	1 and @ay<1999	USEPAT; EPC; JPC; DEFWEN T; IBM_TD E	2002/07/15 09:04
3	BFS	L3	5418	wafer and adhesive and glass	USEPAT; EPC; JPC; DEFWEN T; IBM_TD B	2002/07/15 12:01
4	BFS	L4	2523	3 and via	USEPAT; EPC; JPC; DEFWEN T; IBM_TD E	2002/07/15 11:08
5	BRS	L5	466253	4 ball	USEPAT; EPC; JPC; DEFWEN T; IBM_TI B	2002/07/15 11:16
6	BRS	L6	466	4 and ball	USEPAT; EPC; JPC; DEFWEN T; IBM_TI	2002/07/15 11:17

	Type	L #	Hits	Search Text	DBs	Time Stamp
7	BFS	L7	326	d and Gay:1999	USPAT; EPO; JPO; DEFWEN T; IBM_TI B	2002/07/15 11:09
8	BFS	L8	396	wafer and adhesive and (glass adj (sheet layer))	USPAT; EPO; JPO; DEFWEN T; IBM_TD B	2002/07/15 12:11
9	BFS	L9	180	wafer and ((chip adj scale adj package) csp) and glass	USPAT; EPO; JPO; DEFWEN T; IBM_TD B	2002/07/15 12:12